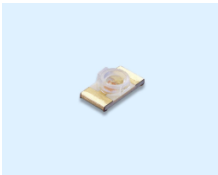


Reverse Package Infrared LED

EAISR3216A0



Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel
- Pb free
- The product itself will remain within RoHS compliant version.

Descriptions

- EAISR3216A0 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.

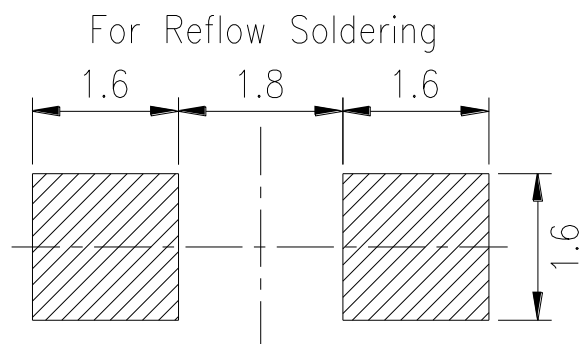
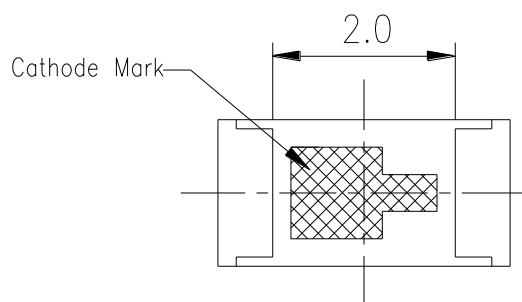
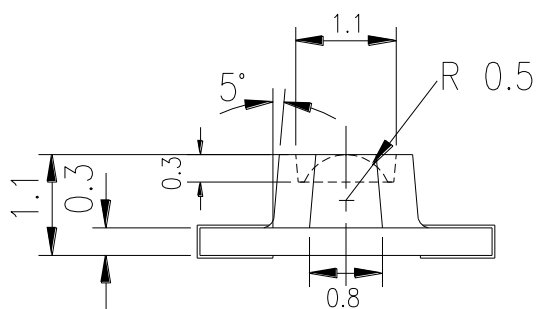
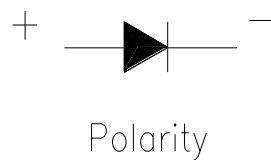
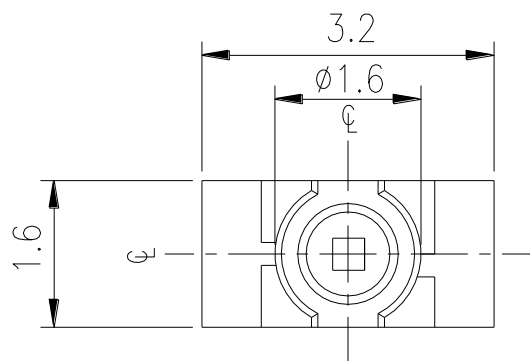
Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Device Selection Guide

LED Part No.	Chip Material	Lens Color
EAISR3216A0	GaAlAs	Water Clear

Package Dimensions



- Notes:** 1.All dimensions are in millimeters
2.Tolerances unless dimensions $\pm 0.1\text{mm}$

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I _F	65	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-25 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	130	mW
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Notes: Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	E _e	I _F =20mA	0.5	1.5	--	mW /sr
		I _F =100mA Pulse Width ≤ 100 μs ,Duty ≤ 1%	--	7.5	--	
Peak Wavelength	λ _p	I _F =20mA	--	940	--	nm
Spectral Bandwidth	Δλ	I _F =20mA	--	45	--	nm
Forward Voltage	V _F	I _F =20mA	--	1.2	1.5	V
		I _F =100mA Pulse Width ≤ 100 μs ,Duty ≤ 1%	--	1.4	1.8	
		I _F =1A	--	2.6	4.0	
Reverse Current	I _R	V _R =5V	--	--	10	μA
View Angle	2θ 1/2	I _F =20mA	--	160	--	deg

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.
Ambient Temperature

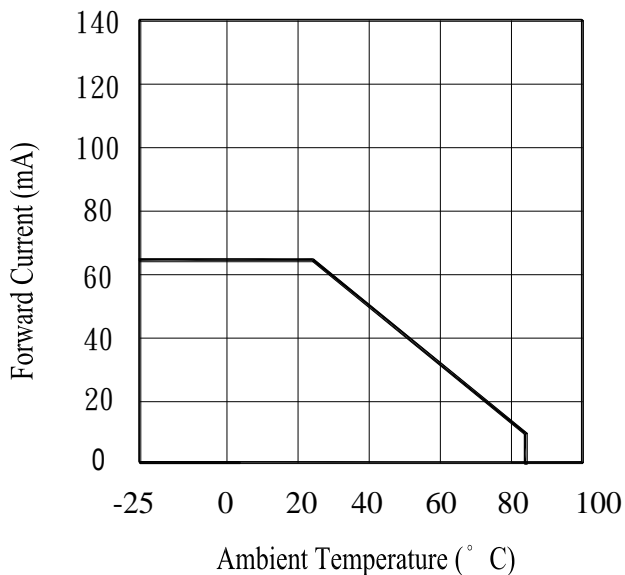


Fig.2 Spectral Distribution

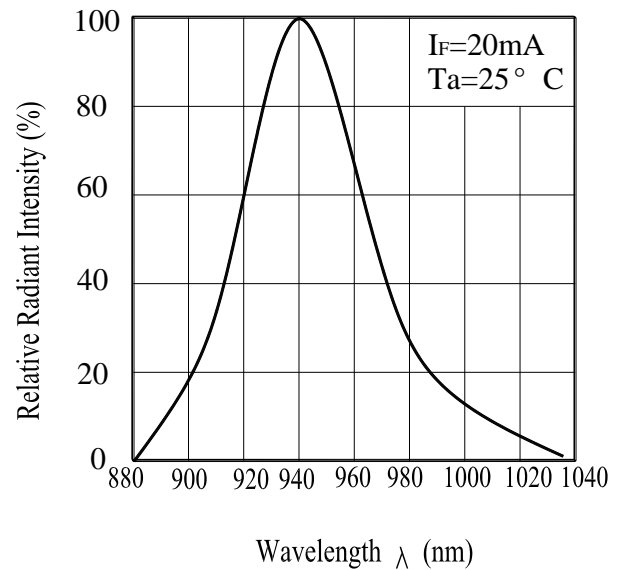


Fig.3 Peak Emission Wavelength
Ambient Temperature

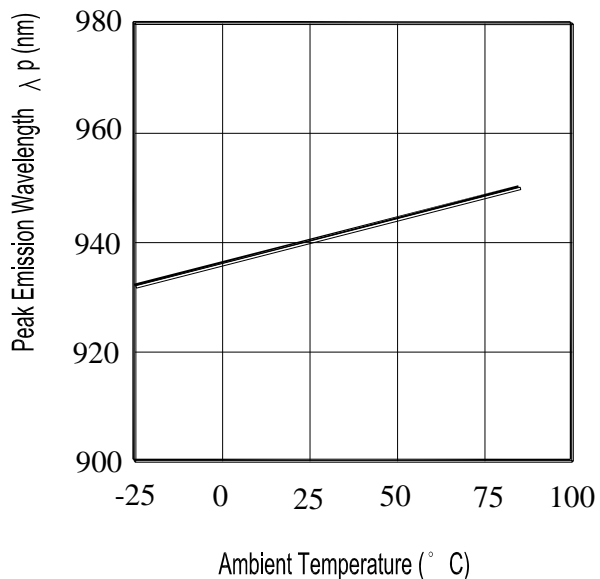
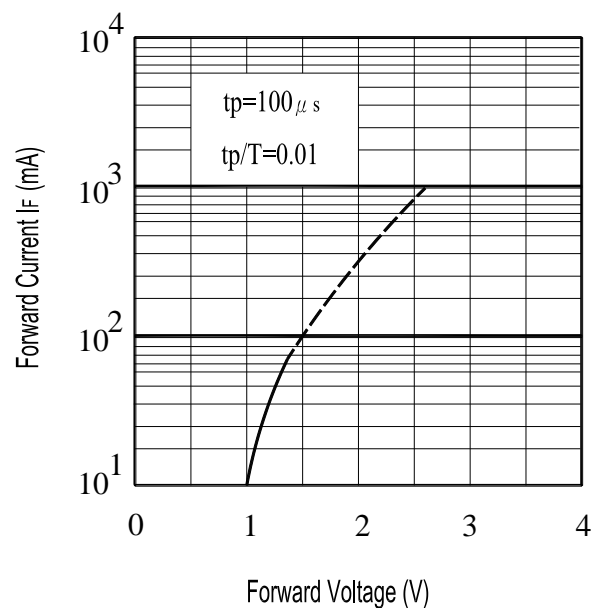


Fig.4 Forward Current
vs. Forward Voltage



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Intensity vs.
Forward Current

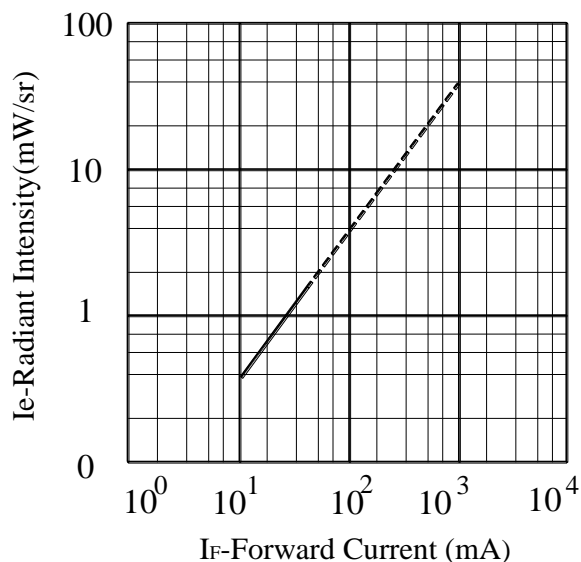


Fig.6 Relative Radiant Intensity vs.
Angular Displacement

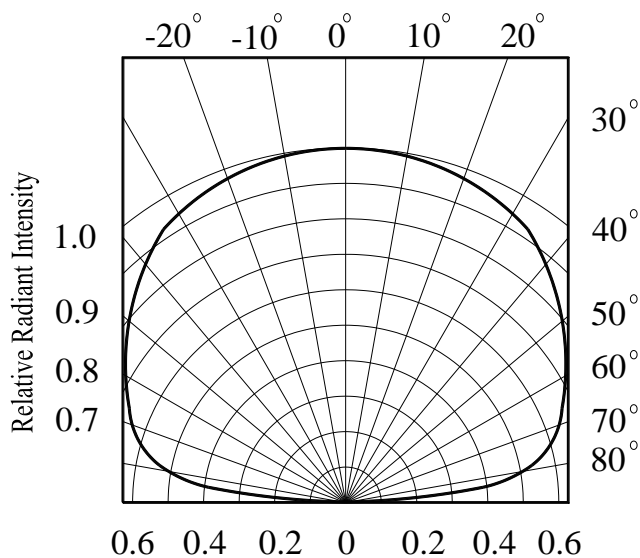


Fig.7 Relative Intensity vs.
Ambient Temperature($^\circ\text{C}$)

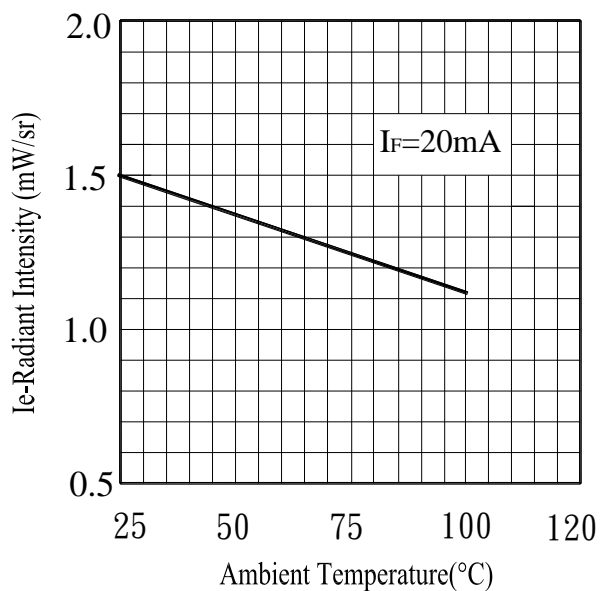
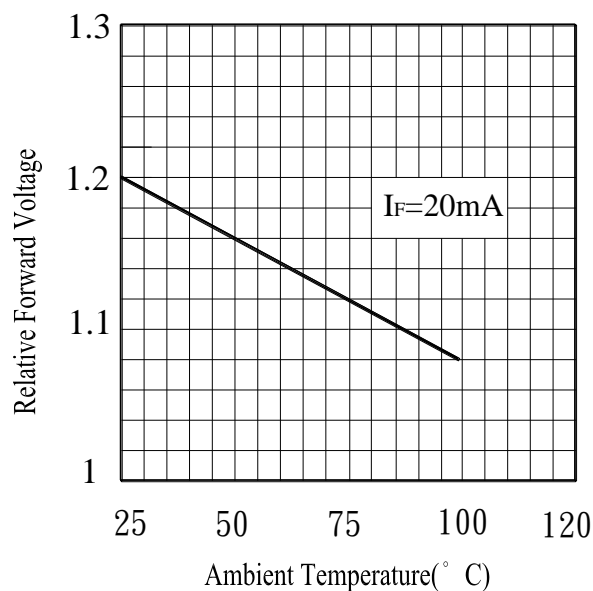


Fig.8 Forward Voltage vs.
Ambient Temperature($^\circ\text{C}$)



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

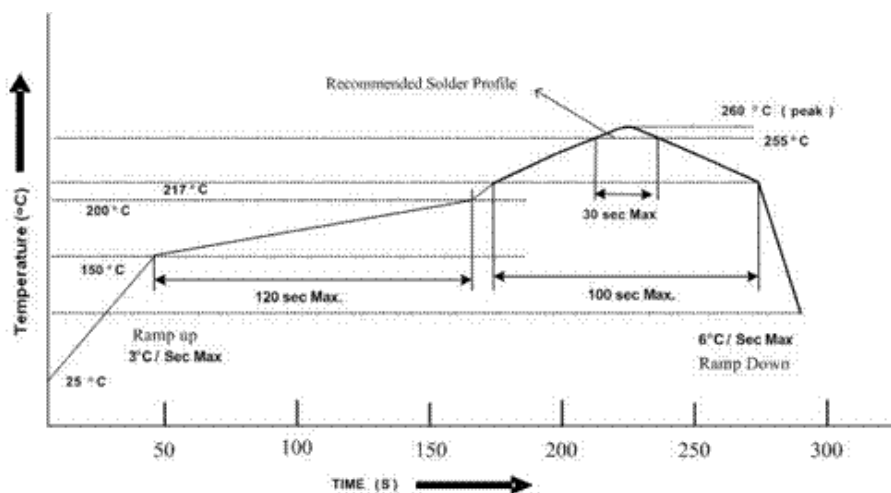
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 48 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

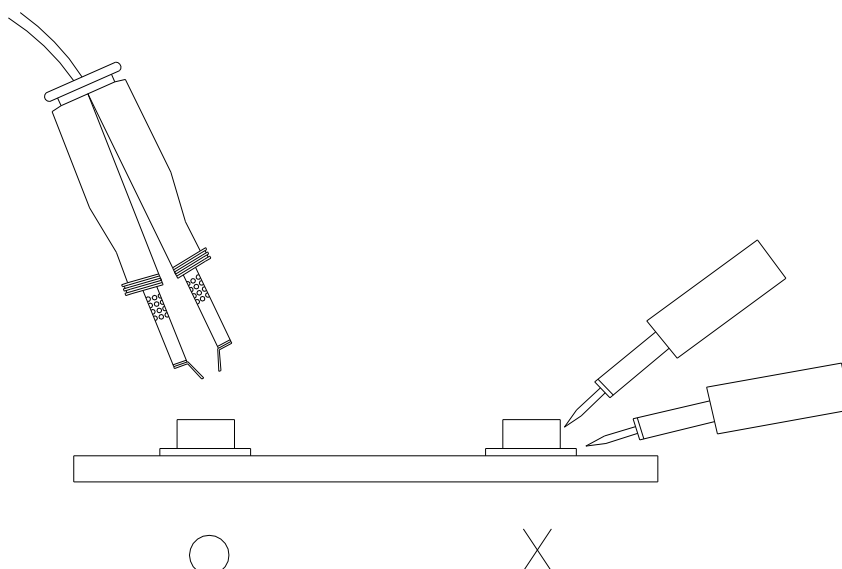
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

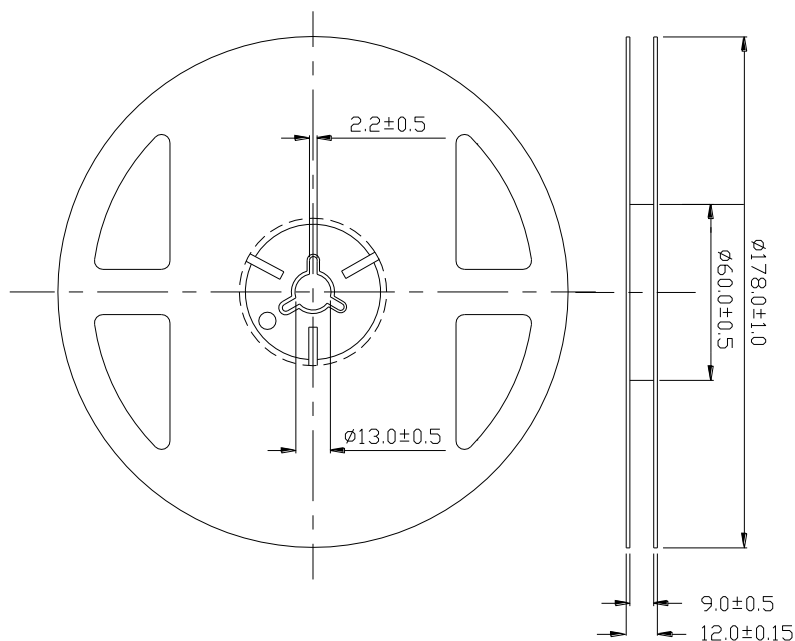
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

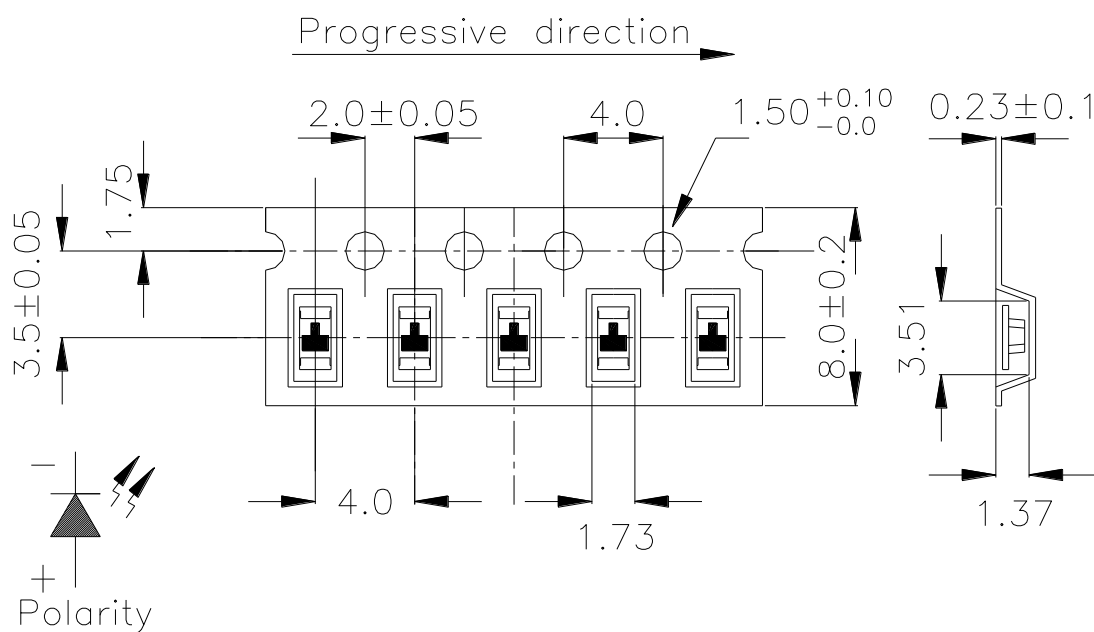
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Package Dimensions



Taping Dimensions



Unit:mm

Label Form Specification

Pb **EVERLIGHT AMERICA**

CPN: XXXXXXXXXXXX
P/N: XXXXXXXXXXXX
XXXXXXXXXXXXXXXXXXXX
QTY: XXXX CAT: XXX
HUE: XXX
REF: XXX
LOT NO: XXXXXXXXXXXXXXXXXXXX
XXXXXXXXXXXXXXXXXXXX
REFERENCE: XXXXXXXXXXXX
XXXXXXXXXXXXXXXXXXXX
MADE IN TAIWAN

CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

Notes

1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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